



RELIABILITY REPORT  
FOR  
MAX6829SYUT-T  
PLASTIC ENCAPSULATED DEVICES

November 12, 2010

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

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## Conclusion

The MAX6829SYUT-T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX6826-MAX6831 are ultra-low-voltage microprocessor ( $\mu$ P) supervisory circuits designed to monitor two power supplies and have manual reset and watchdog input functions. These devices assert a system reset if any of the monitored supplies fall below the preprogrammed thresholds, and maintain reset for a minimum timeout period after the supplies rise above the threshold. Microprocessor supervisors significantly improve system reliability and accuracy compared to separate ICs or discrete components. These devices monitor primary voltages from +1.8V to +5.0V and secondary voltages from +0.9V to +2.5V. These devices are guaranteed to be in the correct state for VCC down to +1.0V. A variety of preprogrammed reset threshold voltages are available (see the Threshold Suffix Guide). The devices include manual reset and watchdog inputs. The MAX6829/MAX6830/MAX6831 provide a factory-trimmed threshold to monitor a 2nd voltage down to +0.9V. The MAX6826/MAX6829 have a push-pull active-low RESET, the MAX6827/MAX6830 have a push-pull RESET and the MAX6828/MAX6831 have an open-drain active-low RESET. The MAX6826/MAX6827/MAX6828 have an auxiliary monitor that allows user adjustable input to monitor voltages down to +0.6V. See *Selector Guide* for functions available.

**II. Manufacturing Information**

A. Description/Function:	Dual, Ultra-Low-Voltage SOT23 $\mu$ P Supervisors with Manual Reset and Watchdog Timer
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	December 29, 2000

**III. Packaging Information**

A. Package Type:	6-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	85Sn/15Pb plate
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0125
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	115°C/W
K. Single Layer Theta Jc:	80°C/W
L. Multi Layer Theta Ja:	N/A
M. Multi Layer Theta Jc:	N/A

**IV. Die Information**

A. Dimensions:	45 X 35 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	$\text{SiO}_2$
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 316 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 3.5 \times 10^{-9}$$

$$\lambda = 3.5 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

### B. E.S.D. and Latch-Up Testing (lot I0AIBA004L, D/C 0114)

The MS61-8 die type has been found to have all pins able to withstand a HBM transient pulse of +/-600V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX6829SYUT-T**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)					
	Ta = 135°C	DC Parameters	80	0	IOEAQ002A, DC 0038
	Biased	& functionality	78	0	IOAJBA004M, DC 0014
	Time = 192 hrs.		79	0	IOAJAQ003B, DC 0039
			79	0	IOAGAQ002B, DC 0038

Note 1: Life Test Data may represent plastic DIP qualification lots.